

# Declaration of Compliance

**Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 and Delegated Directive (EU) 2015/863 of the European Parliament and Council of March 31, 2015, on the restriction of the use of certain hazardous substances in electrical and electronic equipment.**

Regulatory Model	Product Name
NXS2U1NL12G810 *	Converged Server/Storage System

\* NXS2U1NL12G810 will cover NX-3155G-G8 models and its Options (Part numbers starting with C-), Upgrades (Part numbers starting with U-) and Spares/FRU (Part numbers starting with X-).

The above listed product or product family has been verified to be **in compliance** with the European Union Restriction of Hazardous Substances, Directive 2011/65/EU and Delegated Directive (EU) 2015/863.

This declaration is based in part on information provided to Nutanix by its suppliers. To the best of our knowledge, the above listed product does not contain Lead (0.1 % w/w), Mercury (0.1 % w/w), Cadmium (0.01 % w/w), Hexavalent chromium (0.1 % w/w), Polybrominated biphenyls (PBB) (0.1 % w/w), Polybrominated diphenyl ethers (PBDE) (0.1 % w/w), Bis(2-Ethylhexyl) phthalate (DEHP) (0.1 % w/w), Benzyl butyl phthalate (BBP) (0.1 % w/w), Dibutyl phthalate (DBP) (0.1 % w/w), or Diisobutyl phthalate (DIBP) (0.1 % w/w) except where valid exemptions have been granted by the European Union.

The following exemptions were used to achieve compliance:

- 6a(i). Lead as an alloying element in steel for machining purposes containing up to 0.35% lead by weight and in batch hot dip galvanised steel components containing up to 0.2% lead by weight
- 6b(ii). Lead as an alloying element in aluminium for machining purposes with a lead content up to 0.4% by weight
- 6c. Copper alloy containing up to 4 % lead by weight
- 7a. Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)
- 7c(i). Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
- 13(a). Lead in white glasses used for optical applications
- 15(a). Lead in solders to complete a viable electrical connection between the semiconductor die and carrier within integrated circuit flip chip packages where at least one of the following criteria applies:
  - A semiconductor technology node of 90 nm or larger.
  - A single die of 300 mm<sup>2</sup> or larger in any semiconductor technology node.
  - Stacked die packages with die of 300 mm<sup>2</sup> or larger, or silicon interposers of 300 mm<sup>2</sup> or larger.



**Ashok Sarathy**

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